Method of Processing a Substrate

Abstract

The invention relates to methods of processing a substrate (2) having one side (4) and a side (14) being opposite to the one side (4). In particular, the invention relates to a method which comprises providing a protective film (16) having a front surface (18) and a back surface (20) opposite to the front surface (18), and applying a coating of a water-soluble material (22) to at least a central area of the front surface (18) of the protective film (16) and/or applying a coating of a water-soluble material (22) to at least a central portion of the one side (4) of the substrate (2). Subsequently, the protective film (16) is applied to the one side (4) of the substrate (2), wherein the front surface (18) of the protective film (16) faces the one side (4) of the substrate (2) and no adhesive is present between at least the central area of the front surface (18) of the protective film (16) and the one side (4) of the substrate (2). Further, the method comprises applying an external stimulus to the protective film (16) during and/or after applying the protective film (16) to the one side (4) of the substrate (2), so that the protective film (16) is attached to the one side (4) of the substrate (2), and processing the one side (4) of the substrate (2) and/or the side (14) of the substrate (2) being opposite to the one side (4).

[Figure 2]